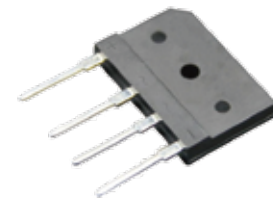


FEATURES

- Ideal For Printed Circuit Board Mounting
- Built-in Printed Circuit Board Stand-offs
- The Plastic Material Used Carries Underwriters Laboratory Flammability Recognition 94V-0
- High Case Dielectric Strength



GBJ

MECHANICAL DATA

- Case: Reliable Low Cost Construction Utilizing Molded Plastic Technique
- Mounting Position: Any

APPROVALS

RoHS Compliance with 2011/65/EU

MAXIMUM RATINGS AND CHARACTERISTICS (T_A=25°C)

Parameter	Symbol	GBJ 35005	GBJ 3501	GBJ 3502	GBJ 3504	GBJ 3506	GBJ 3508	GBJ 3510	Unit
Marking		GBJ 35005	GBJ 3501	GBJ 3502	GBJ 3504	GBJ 3506	GBJ 3508	GBJ 3510	
Maximum Repetitive Peak Reverse Voltage	V _{RRM}	50	100	200	400	600	800	1000	V
Maximum RMS Voltage	V _{RMS}	35	70	140	280	420	560	700	v
Maximum DC Blocking Voltage	V _{DC}	50	100	200	400	600	800	1000	V
Maximum Average Forward Rectified Current @ T _c =100°C	(with heatsinkNote 2)	35.0							A
	(without heatsink)	3.5							A
Peak Forward Surge Current Single Sine-wave Superimposed On Rated Load (Jedec Method)	I _{FSM}	400							A
Maximum Forward Voltage at 10.0A DC	V _F	1.1							V
Maximum DC Reverse Current at rated DC Blocking Voltage Per Element	T _J =25°C	10							μA
	T _J =125°C	500							μA
Typical Thermal Resistance (Note2)	R _{θJC}	1.5							°C/W
Operating Junction and Storage Temperature Range	T _J , T _{STG}	-55 ~ +150							°C

NOTES:

- Measured at 1.0MHz and applied reverse voltage of 4.0V DC.
- Device mounted on 300mm*300mm*1.6mm cu plate heatsink.

CHARACTERISTIC CURVES

Fig. 1-Forward Current Derating Curve

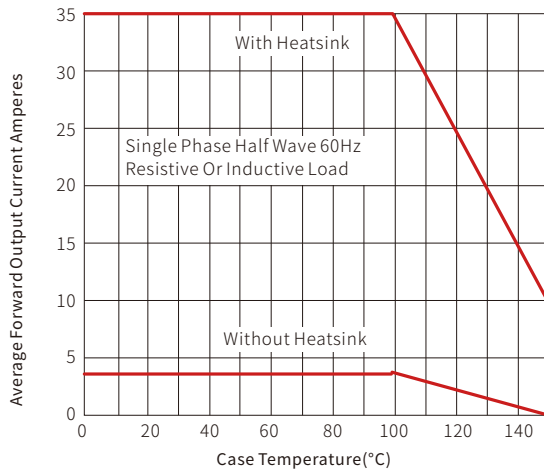


Fig. 2-Maximum Non-Repetitive Surge Current

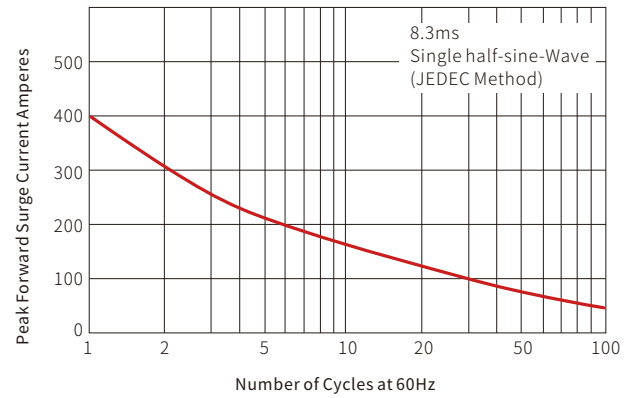


Fig. 3-Typical Junction Capacitance

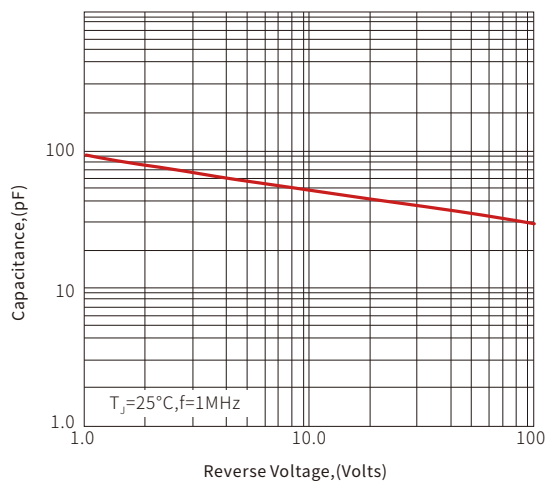


Fig. 4-Typical Forward Characteristics

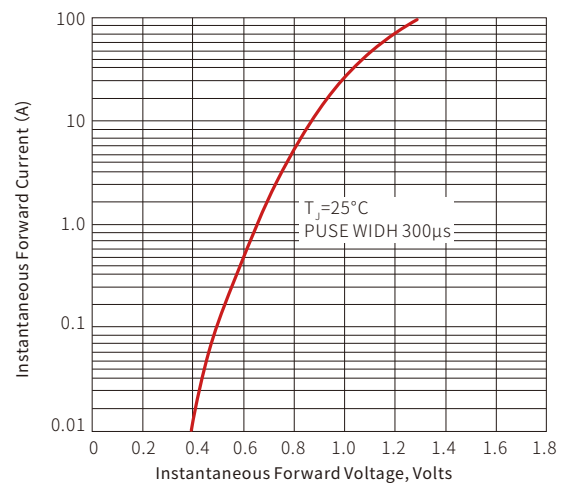
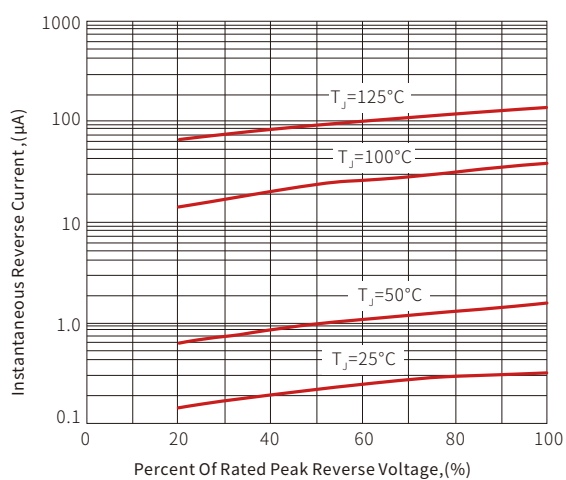
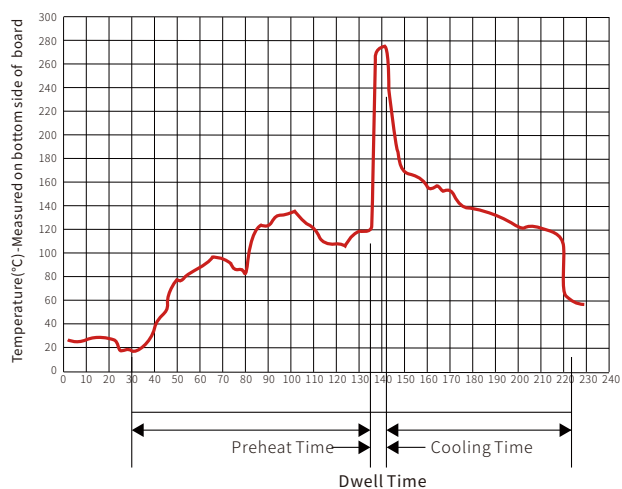


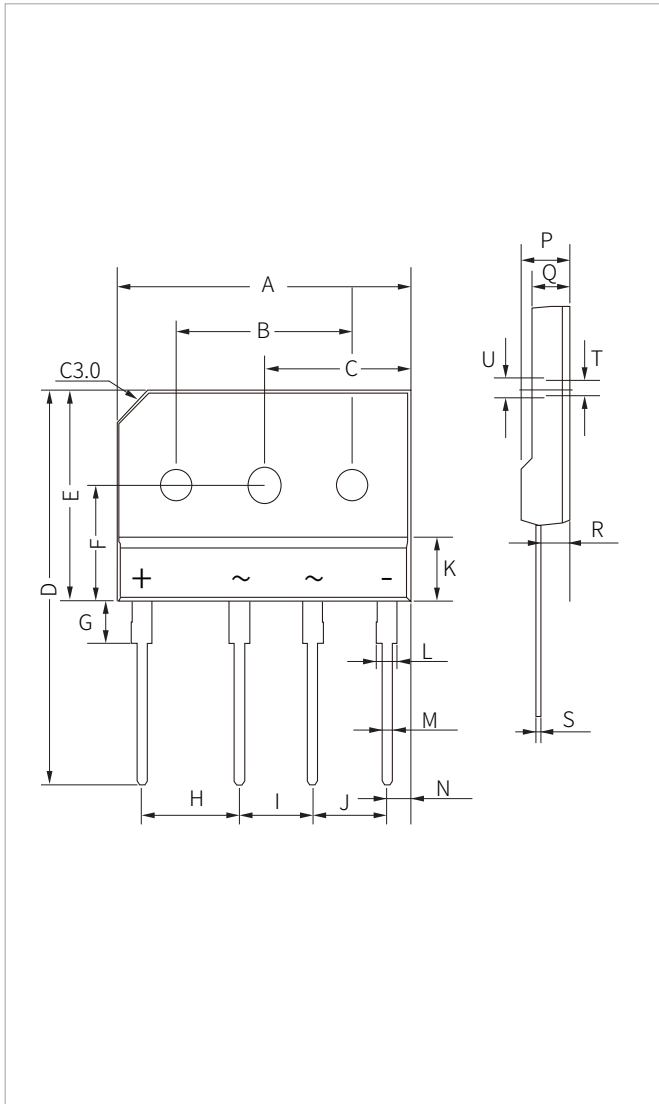
Fig. 5-Typical Reverse Characteristics


WAVE SOLDERING



Wave Parameter		Lead-free assembly
Pre Heat	Temperature Min	100°C
	Temperature Max	150°C
	Time(min to max)	60 – 180 secs
Solder pot Temperature		280°C Max
Solder Dwell Time		2-5 seconds

GBJ PACKAGE INFORMATION



Ref.	Millimeters		Inches	
	Min.	Max.	Min.	Max.
A	29.8	30.4	1.173	1.197
B	17.8	18.2	0.701	0.717
C	14.8	15.2	0.583	0.600
D	37.0	38.5	1.457	1.516
E	19.8	20.4	0.780	0.803
F	10.8	11.2	0.425	0.441
G	3.80	4.20	0.150	0.165
H	9.90	10.10	0.390	0.398
I	7.40	7.60	0.291	0.299
J	7.40	7.60	0.291	0.299
K	5.90	6.10	0.232	0.240
L	1.95	2.15	0.077	0.085
M	0.90	1.10	0.035	0.043
N	2.40	2.60	0.094	0.102
P	4.40	4.80	0.173	0.189
Q	3.40	3.80	0.134	0.150
R	2.50	2.70	0.098	0.106
S	0.55	0.75	0.022	0.030
T	3.10	3.30	0.122	0.130
U	3.40	3.60	0.134	0.142

ORDERING INFORMATION

Part Number	Component Package	Per Box	Description
GBJ35005-GBJ3510	GBJ	250PCS	Box

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By QR Code

Website



Wechat

To find your local partner within Semiware's global website: www.semiware.com

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